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Atty. Dkt. No. 039153-0457 (G1162)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY  
COPPER ALLOY TO OBTAIN A  
LOW RESISTANCE AND LARGE  
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Unknown

Art Unit: Unknown

<b>CERTIFICATE OF MAILING</b> I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below. <b>CHRIS ESCAVAILLE</b> (Printed Name) <i>Chris Escaville</i> (Signature) <b>9-23-02</b> (Date of Deposit)
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**TRANSMITTAL OF FORMAL DRAWINGS**Commissioner for Patents  
Washington, D.C. 20231

ATTENTION: DRAWING REVIEW BRANCH

Sir:

Transmitted herewith are the formal drawings (9 sheets, Figures 1-7) for the above-identified application. The Official Draftsperson is respectfully requested to approve these drawings for entry into the application.

Respectfully submitted,

Date Sept. 23, 2002By *Paul S. Hunter*

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